

U.S. Patent Application Serial No. 09/976,278

Response dated December 12, 2003

Reply to OA of July 14, 2003

IN THE CLAIMS

Please cancel claims 2-4 without prejudice or disclaimer.

Please amend claims 1 and 5 as follows:

1. (Currently Amended): A positive photosensitive resin composition comprising:

(A) a positive photosensitive resin component which is a carboxyl- and/or hydroxyphenyl-containing resin (a) in combination with an ether linkage-containing olefinic unsaturated compound (b),

(B) a photoacid generator and

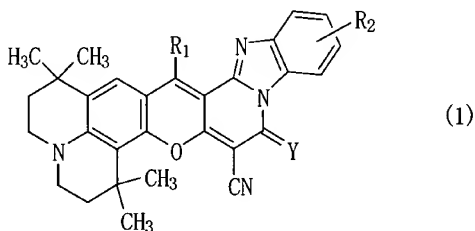
(C) a photosensitizer which is a benzopyran condensed ring compound capable of increasing photosensitivity to visible light with a wavelength of 480 nm or more.

2 - 4. (Canceled).

5. (Currently Amended): A composition according to claim 4 1, wherein the proportion of the unsaturated compound (b) is about 5 to 150 parts by weight per 100 parts by weight of the resin (a).

6. (Original): A composition according to claim 1, wherein the proportion of the photoacid generator (B) is about 0.1 to 40 parts by weight per 100 parts by weight of the resin (A).

7. (Original): A composition according to claim 1, wherein the photosensitizer (C) is a benzopyran condensed ring compound represented by Formula (1)



wherein R₁ is hydrogen, halogen, cyano, trifluoromethyl, carboxyl or carboxylic acid ester, R₂ is hydrogen, alkyl, alkoxy, cyano, trifluoromethyl, sulfoxy or halogen, and Y is NH or O.

8. (Original): A composition according to claim 1, wherein the proportion of the photosensitizer (C) is about 0.1 to 10 parts by weight per 100 parts by weight of the total amount of the resin (A) and photoacid generator (B).

9. (Original): A composition according to claim 1 which further comprises, as a photoacid proliferating agent (D), an organic acid ester and/or a crosslinked carbocyclic compound containing a crosslinked carbocyclic skeleton which has a hydroxyl group or groups bonded to any of the crosslinked carbocyclic rings and, at a carbon atom or atoms adjacent to the hydroxyl-bearing carbon

atom or atoms, a sulfonate group represented by Formula (2)



wherein R₅ is acyl, aliphatic hydrocarbon, polycyclic aromatic hydrocarbon or a heterocyclic group.

10. (Original): A composition according to claim 1, which is an organic solvent-based resin composition.

11. (Original): A composition according to claim 1, which is an aqueous resin composition.

12. (Original): A positive photosensitive dry film prepared by applying a positive photosensitive resin composition according to claim 1 to a surface of support film, followed by drying, to thereby form a positive photosensitive resin layer.

13. (Original): A method of forming a pattern comprising the steps of:

- (1) applying a positive photosensitive resin composition according to claim 1 to a substrate, followed by drying, to form a positive photosensitive resin coating,
- (2) irradiating the resin coating with visible light directly or through a mask so as to obtain a desired pattern, and
- (3) removing the irradiated part of the positive photosensitive resin coating by development to form a resist pattern coating.

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14. (Original): A method of forming a pattern comprising the steps of:

- (1') attaching a positive photosensitive dry film according to claim 12 to a substrate so that the photosensitive resin layer of the dry film is in contact with the substrate to form a positive photosensitive resin coating, and optionally peeling off the support film of the dry film,
- (2) irradiating the resin coating with visible light directly or through a mask so as to obtain a desired pattern, and
- (3') peeling off the support film of the dry film when the support film has not been peeled off, and removing the irradiated part of the positive photosensitive resin coating by development to form a resist pattern coating.